

Supplementary file

Inkjet printing technology for increasing the I/O density of 3D TSV interposers

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Table S1 Printing parameters for printing fresh InkOrmo polymer with the Dimatix

Cartridge setting	
Jetting voltage (Volts)	27.3
Cartridge temperature (in C)	30
Substrate temperature (in C)	28
Meniscus vacuum (inches H ₂ O)	4.0
Cartridge print height (mm)	0.8

Table S2 Printing parameters used for printing the UBM pads with SIJ

Waveform	Sine wave
Amplitude [V]	453
Bias (DC) [V]	0 (on top of dielectric)
ON speed [mm s ⁻¹]	0.30
Frequency [Hz]	70
Spiral pitch [μm]	15
Number of layers	~60

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